

CLAIMS

We claim:

1. A method of electrically grounding a circuit board to a chassis comprising the steps of:

attaching an electrically conducting mounting stud to the chassis;
attaching a ground clip adjacent a mounting hole on the circuit board;
positioning the mounting stud through the mounting hole; and
positively engaging the ground clip with the mounting stud.

2. The method of claim 1, wherein the ground clip is attached to an upper surface of the circuit board.

3. The method of claim 1, wherein the step of attaching a ground clip includes soldering the ground clip to the circuit board.

4. The method of claim 3, wherein the step of attaching a ground clip includes extending ground clip leads through lead holes in the circuit board.

5. The method of claim 1, further comprising the step of mounting the circuit board to the chassis by extending a mounting stud nose through the mounting hole.

6. The method of claim 1, wherein the step of positively engaging the ground clip with the mounting stud includes receiving a mounting stud nose in a biased clip opening.

7. A ground clip apparatus for electrically grounding a circuit board to a chassis, the apparatus comprising:

a generally circular upper body portion having a side opening; and
a plurality of retentive leads extending from the upper body portion, the plurality of retentive leads adapted for insertion through holes in the circuit board.

8. The apparatus of claim 7, further comprising a plurality of stanchions extending from the lower end of the upper body portion.

9. The apparatus of claim 7, wherein each retentive lead is biased to provide a retention force.

10. The apparatus of claim 9, wherein each retentive lead includes a teat.

11. The apparatus of claim 7, wherein the upper body portion includes outwardly flared ends adjacent the side opening.

12. The apparatus of claim 7, wherein the plurality of retentive leads are substantially opposite the side opening.

13. In a printed circuit board adapted for mounting in a chassis having a plurality of mounting studs having an upper nose, the printed circuit board having a plurality of mounting holes adapted to receive the upper nose of the mounting studs, the improvement comprising:

a plurality of ground clips, each ground clip having a generally circular upper body portion with a side opening, and a plurality of retentive leads extending from the upper body portion, each ground clip connected to the printed circuit board around a portion of a mounting hole,

wherein the generally circular upper body portion is in contact with the upper nose to provide electrical grounding of the printed circuit board to the chassis.

14. The improvement of claim 13, wherein each ground clip is positioned so that the side opening faces the mounting hole.

15. The improvement of claim 13, wherein the printed circuit board includes a plurality of lead holes for each ground clip, the plurality of lead holes corresponding to the plurality of retentive leads of each ground clip, the retentive leads inserted into the lead holes for attaching each ground clip to the printed circuit board.

16. The improvement of claim 15, wherein each retentive lead is biased to provide a retention force.

17. The improvement of claim 15, wherein the plurality of retentive leads are substantially opposite the side opening.

18. The improvement of claim 13, further comprising a plurality of stanchions extending from the lower end of the upper body portion.

19. The improvement of claim 13, wherein the upper body portion includes outwardly flared ends adjacent the side opening.

20. The improvement of claim 19, wherein the outwardly flared ends are allowed to flex outwardly to receive the upper nose of the mounting stud.